



Material Content Data Sheet



Sales Product Name		IGD06N60T		Issued		25. January 2018		
MA#		MA001701942						
Package		PG-TO252-3-342		Weight*		332.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.812	0.24	0.24	2441	2441
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		482	
	non noble metal	copper	7440-50-8	160.096	48.10	48.16	481024	481650
	non noble metal	aluminium	7429-90-5	0.472	0.14	0.14	1417	1417
wire	non noble metal	aluminium	7429-90-5	0.472	0.14	0.14	1417	1417
encapsulation	organic material	carbon black	1333-86-4	1.174	0.35		3529	
	plastics	epoxy resin	-	16.442	4.94		49401	
	inorganic material	silicondioxide	60676-86-0	129.187	38.82	44.11	388154	441084
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11237	11237
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1573	1573
solder	non noble metal	tin	7440-31-5	0.019	0.01		58	
	noble metal	silver	7440-22-4	0.024	0.01		73	
	non noble metal	lead	7439-92-1	0.923	0.28	0.30	2772	2903
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		58	
	non noble metal	copper	7440-50-8	19.177	5.76	5.77	57620	57695
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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